Ordering Information

Part Number		Part Marking ⁽¹⁾		Soft-Start	Load Discharge	Bookogo
Standard	Pb-Free	Standard	Pb-Free	Son-Start	Load Discharge	Package
MIC94060BC6	MIC94060YC6	P54	<u>P5</u> 4			
MIC94061BC6	MIC94061YC6	P55	<u>P5</u> 5		•	00.70.0
MIC94062BC6	MIC94062YC6	P56	<u>P5</u> 6	•		SC-70-6
MIC94063BC6	MIC94063YC6	P57	<u>P5</u> 7	•	•	
	MIC94060YMT	_	P54			
_	MIC94061YMT	_	P55		•	1.2mm x 1.6mm
_	MIC94062YMT	_	P56	•		Thin MLF ^{® (2, 3)}
_	MIC94063YMT	_	P57	•	•	

Notes

- 1. Underbar symbol on SC-70 Pb-free packages may not be to scale.
- 2. MLF[®] ▲ = Pin 1 identifier.
- 3. MLF® is a GREEN RoHS compliant package. Lead finish is NiPdAu. Mold compound is Halogen Free.

Pin Configuration



Pin Description

Pin Number SC-70 MLF Pin Name		Din Nama	Pin Function			
		Pin Name				
1	1	V_{OUT}	Drain of P-channel MOSFET.			
2,5	2	GND	Ground and the backside pad (MLF only) should both be connected to electrical ground.			
4	3	V_{IN}	Source of P-channel MOSFET.			
3	4	EN	Enable (Input): Active-high CMOS compatible control input for switch A. Do not leave floating.			
6		NIC	No Internal Connection. A signal or voltage applied to this pin will have no effect on device operation.			

Absolute Maximum Ratings (1)

Input Voltage (V _{IN})	+6V
Enable Voltage (V _{EN})	
Continuous Drain Current (I _D) (3)	
T _A = 25°C	±2A
T _A = 85°C	±1.4A
Pulsed Drain Current (I _{DP}) (4)	±6A
Continuous Diode Current (I _S) (4)	–50mA
Storage Temperature (T _s)	55°C to +150°C
ESD Rating – HBM (6)	4KV

Operating Ratings (2)

Input Voltage (V _{IN})	+1.7 to +5.5V
Junction Temperature (T _A)	40°C to +125°C
Package Thermal Resistance	
SC-70-6 (θ _{JA})	240°C/W
1.2x1.6 MLF (θ_{JA})	172°C/W
1.2x1.6 MLF $(\theta_{JC})^{(3)}$	134°C/W

Electrical Characteristics

 V_{IN} = 5V; T_A = 25°C, bold values indicate -40°C $\leq T_A \leq +85$ °C, unless noted.

Symbol	Parameter	Condition	Min	Тур	Max	Units
V_{EN_TH}	Enable Threshold Voltage	V_{IN} = 1.8V to 4.5V, I_{D} = -250 μ A	0.5		1.2	V
		V_{IN} = 1.7V to 4.5V, I_{D} = -250 μ A	0.4		1.2	V
I _{EN}	Enable Input Current	$V_{IN} = V_{EN} = 5.5V$		2	4	μA
I _{VIN}	OFF State Leakage Current	$V_{IN} = +5.5V, V_{EN} = 0V$			1	μA
R _{DS(ON)}	P-Channel Drain to Source ON Resistance	V_{IN} = +4.5V, ID = -100mA, V_{EN} = 1.5V		77	110	mΩ
		V_{IN} = +3.6V, ID = -100mA, V_{EN} = 1.5V		85	115	mΩ
	SC-70 Package	V_{IN} = +2.5V, ID = -100mA, V_{EN} = 1.5V		100	140	mΩ
		V_{IN} = +1.8V, ID = -100mA, V_{EN} = 1.5V		145	200	mΩ
		V_{IN} = +1.7V, ID = -100mA, V_{EN} = 1.5V		155	215	mΩ
R _{DS(ON)}	P-Channel Drain to Source ON Resistance	V_{IN} = +4.5V, ID = -100mA, V_{EN} = 1.5V		85	115	mΩ
		V_{IN} = +3.6V, ID = -100mA, V_{EN} = 1.5V		100	140	mΩ
	MLF Package	V_{IN} = +2.5V, ID = -100mA, V_{EN} = 1.5V		145	200	mΩ
		V_{IN} = +1.8V, ID = -100mA, V_{EN} = 1.5V		155	215	mΩ
		V_{IN} = +1.7V, ID = -100mA, V_{EN} = 1.5V		165	225	mΩ
R _{SHUTDOWN}	Turn-Off Resistance	V_{IN} = +3.6V, I_{TEST} = 1mA, V_{EN} = 0V		200	300	Ω
		MIC94061, 63				

Dynamic

Symbol	Parameter	Condition	Min	Тур	Max	Units
t _{ON_DLY}	Turn-On Delay Time	$V_{IN} = +3.6V$, ID = -100 mA, $V_{EN} = 1.5V$		0.85	1.5	μs
		MIC94060, 61				
		$V_{IN} = +3.6V$, ID = -100 mA, $V_{EN} = 1.5V$		700	1200	μs
		MIC94062, 63				
t _{ON_RISE}	Turn-On Rise Time	$V_{IN} = +3.6V$, ID = -100 mA, $V_{EN} = 1.5V$	0.5	1	5	μs
		MIC94060, 61				
		$V_{IN} = +3.6V$, ID = -100 mA, $V_{EN} = 1.5V$	500	800	1500	μs
		MIC94062, 63				

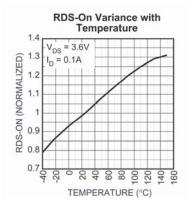
Dynamic (Continued)

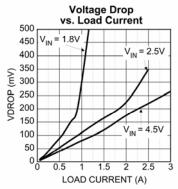
t _{OFF_DLY}	Turn-Off Delay Time	V _{IN} = +3.6V, ID = -100mA, V _{EN} = 1.5V	100	200	ns
		MIC94060, 61			
		V_{IN} = +3.6V, ID = -100mA, V_{EN} = 1.5V	60	200	ns
		MIC94062, 63			
t _{OFF_FALL}	Turn-Off Fall Time	V_{IN} = +3.6V, ID = -100mA, V_{EN} = 1.5V	60	100	ns
		MIC94060, 61			
		V_{IN} = +3.6V, ID = -100mA, V_{EN} = 1.5V	60	100	ns
		MIC94062, 63			

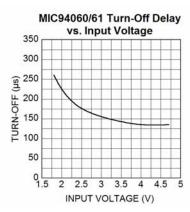
Notes:

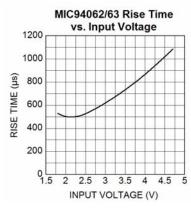
- 1. Exceeding the absolute maximum rating may damage the device.
- 2. The device is not guaranteed to function outside its operating rating.
- 3. With backside thermal contact to PCB.
- 4. Pulse width $<300\mu s$ with <2% duty cycle.
- Continuous body diode current conduction (reverse conduction, i.e. V_{OUT} to V_{IN}) is not recommended.
- 6. Devices are ESD sensitive. Handling precautions recommended. HBM (Human body model), 1.5kΩ in series with 100pF.

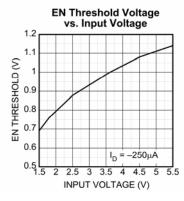
Typical Characteristics

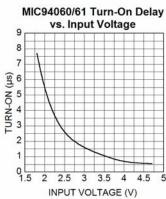


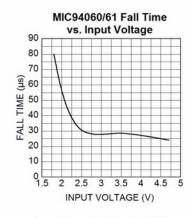


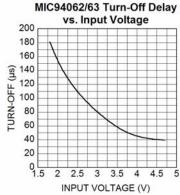


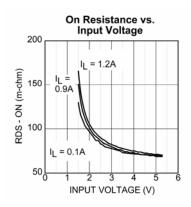


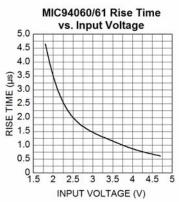


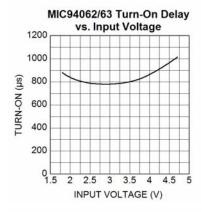


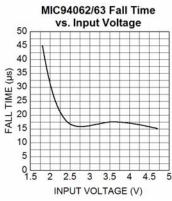




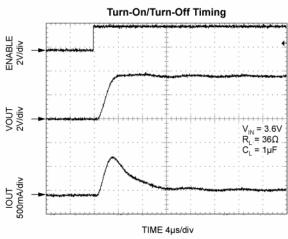


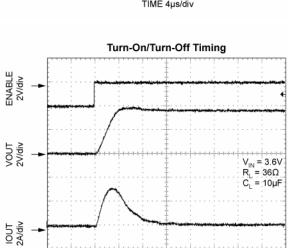




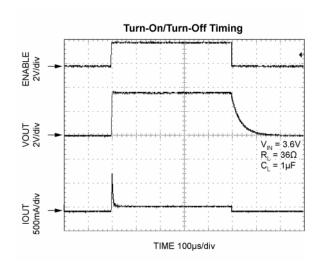


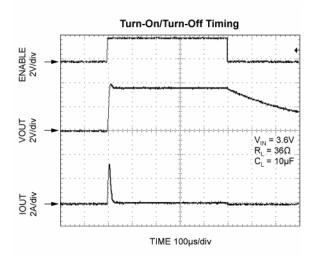
Functional Characteristics MIC94060



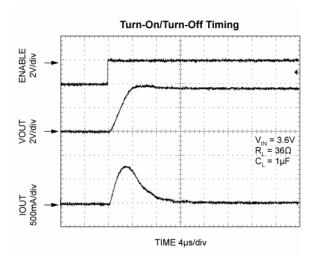


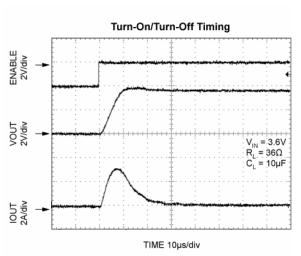
TIME 10µs/div

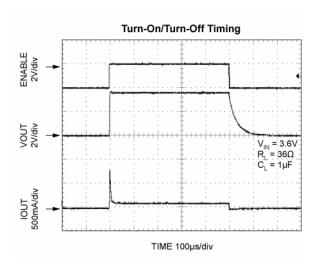


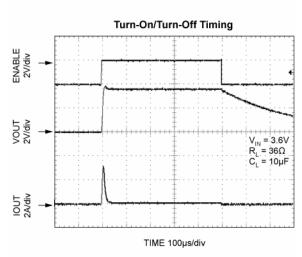


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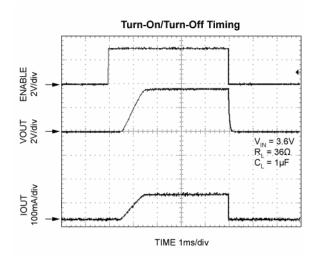


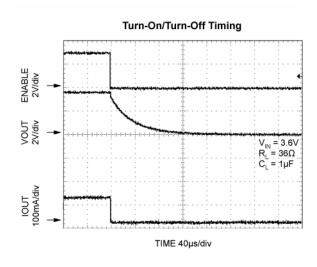


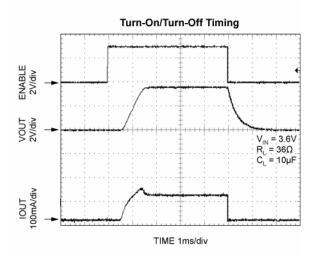


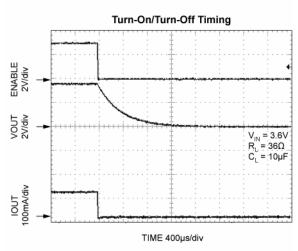


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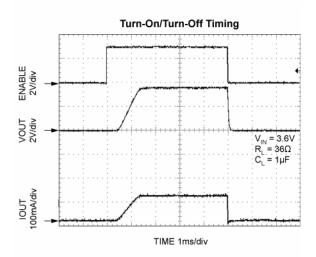


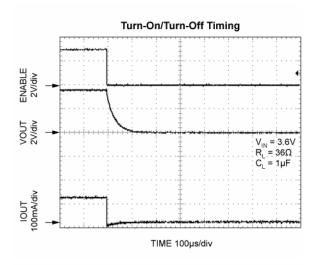


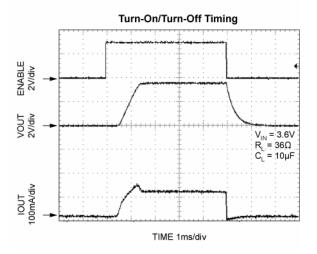


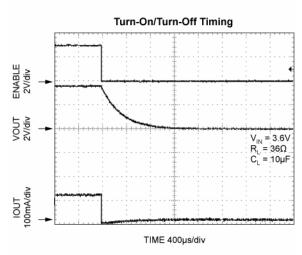


MIC94063

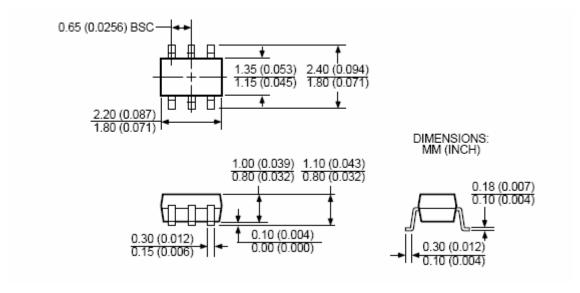




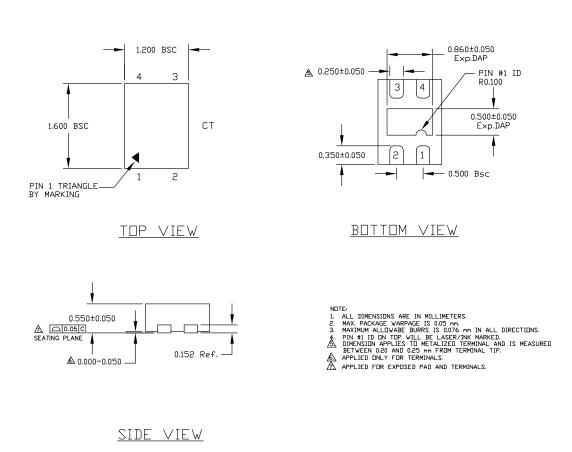




Package Information

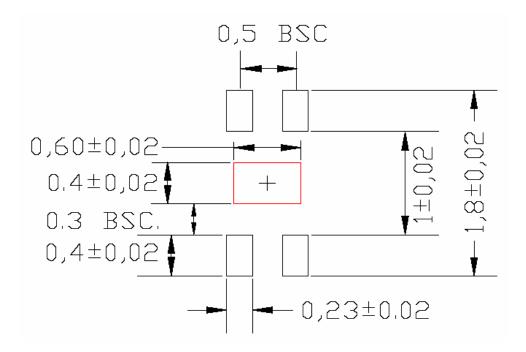


6-Pin SC-70 (C6)



4-Pin Thin MLF[®] (MT)

Recommended Land Pattern for MLF 1.2x1.6 4 Lead



Optional for maximum thermal performance. Heatsink should be connected to GND plane of PCB for maximum thermal performance.

Disclaimer: This is only a recommendation based on information available to Micrel from its suppliers. Actual land pattern may have to be significantly different due to various materials and processes used in PCB assembly. Micrel makes no representation or warranty of performance based on the recommended land pattern."

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